

Title (en)

METHOD FOR PRODUCTION OF PIECES FOR PASSIVE ELECTRONIC COMPONENTS

Title (de)

VERFAHREN ZUR HERSTELLUNG DER BAUTEILE FÜR PASSIVE ELEKTRONISCHE BAUELEMENTE

Title (fr)

PROCEDE DE FABRICATION DE PIECES POUR COMPOSANTS ELECTRONIQUES PASSIFS

Publication

**EP 1637017 A2 20060322 (FR)**

Application

**EP 04767412 A 20040622**

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Abstract (en)

[origin: WO2005002308A2] The invention relates to a method for production of pieces for passive electronic components in which: a layered strip (1) is produced, made from at least one stack of a thin metal strip and a layer of adhesive material, at least one piece (6) is cut from the layered strip (1), the cutting being carried out by a method including at least one etching step with sand. The invention further relates to the pieces obtained.

IPC 1-7

**H05K 3/00**; **H01F 41/02**

IPC 8 full level

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Citation (search report)

See references of WO 2005002308A2

Citation (examination)

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- US 4364020 A 19821214 - LIN KOU C, et al
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